

## ABSTRACT OF THE INVENTION

An integrated heat dissipation device includes a heat sink portion having a base with a plurality of posts formed thereon, a fin portion with a plurality of stacked fins, individually formed over the heat sink portion, and at least two L-shaped heat pipes installed in the heat sink portion and extended to the fin portion. The heat pipes are staggeredly arranged to have a well-proportioned scatteration in the fin portion such that the heat conducted by the heat pipes can be uniformly distributed to the fins for dissipation. As such, a heat dissipation device with enhanced heat-dissipating efficiency is obtained.